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Form PTO 1449 (Rev. 2-32) U.S. Department of Commerce Patent and Trademark Office				Atty. Docket No. FOV-053		Serial No. 09/884,863	
Information Disclosure Statement by Applicant				Applicant: Richard B. Merrill			
(Use several sheets if necessary)				Filed: June 18, 2001		Group: 2812 2823	
Foreign Documents							
							Translation
Init.		Document No.	Date	Country	Class	Subclass	Yes No
EW	19	EP 0,605,898	07/13/1994	Japan	H01L	27/146	X
EW	20	WO 98/19455	05/07/1998	Germany	H04N	3/15	X
Other Documents (Including Author, Title, Date, Pertinent Pages, etc.)							
EW	21	S. Chamberlain, "Photosensitivity and Scanning of Silicon Image Detector Arrays", <u>IEEE Journal of Solid-State Circuits</u> , Vol. SC-4, No. 6, pp. 333-342, December 1969					
EW	22	R. Wolfenbuttel et al., "A Novel Approach to Solid-state Colour Sensing", <u>Sensors and Actuators</u> , Vol. 9, pp. 199-211, 1986 (no month).					
EW	23	R. Wolfenbuttel et al., "Performance of an Integrated Silicon Colour Sensor with a Digital Output in Terms of Response to Colours in the Colour Triangle", <u>Sensors and Actuators</u> , Vol. A21-A23, pp. 574-580, 1990 (no month).					
EW	24	P. Seitz et al., "Smart optical and image sensors fabricated with industrial CMOS/CCD semiconductor processes", <u>SPIE</u> , Vol. 1900, pp. 21-30, January 1993.					
EW	25	J. Kramer, "Photo-ASICs: Integrated Optical Metrology systems with Industrial CMOS Technology", <u>Doctorial Dissertation: Diss Eth Nr. 10186</u> , MSc Imperial College of Science and Technology, pp. 44-47, 1993.					
EW	26	M. Chouikha, "Color sensitive photodetectors in standard CMOS and BiCMOS technologies", <u>SPIE</u> , VOL. 2950, pp. 108-120, August 1996					
EW	27	H. Wong, "Technology and Device Scaling Considerations for CMOS Imagers", <u>IEEE Transactions on Electron Devices</u> , Vol. 43, No. 12, December 1996					
EW	28	K. Parulski, "Enabling technologies for a family of digital cameras", <u>SPIE</u> , Vol. 2654, Paper 18, pp. 156-163, 1996 (no month)					
EW	29	B. Weibel, "High-end digital cameras can make professional indoor photography a snap", <u>Buyers Guide</u> , pp. 311-317, April 1997					
EW	30	D. Sutherland, "Neaveau Niche-Part 1: The Latest in digital SLRs", <u>Shutterbug</u> , pp. 200-209, November 1997					
EW	31	M. Chouikha, "Buried Triple p-n Junction Structure in a BiCMOS Technology for Color Detection", <u>IEEE BCTM 6.4</u> , pp. 108-111, 1997 (no month).					
EW	32	A. Theuwissen, "Fundamentals of Solid-State Imaging", <u>Solid-State Imaging with Charge-coupled Devices</u> , pp. 131-141, 1995 Reprinted with corrections 1996, 1997					
EW	33	R. Guidash, "A 0.6 um CMOS Pinned Photodiode Color Imager Technology", <u>IEDM</u> , pp. 927-929, 1997 (no month)					
EW	34	D. Knipp, "Low Cost Approach to Realize Novel Detectors for Color Recognition", <u>Proc. ICPS 98</u> (International Congress on Imaging Science), pp. 350-353, September 1998					
EW	35	H. Miura, "A 100 Frame/s CMOS Active Pixel Sensor for 3D-Gesture Recognition System" 1999 IEEE International Solid-State Circuits Conference, pp. 142-143, June 1999					
EW	36	Stiebig et al., "Transient Behavior of Optimized nipiin Three-Color Detectors", <u>IEEE Transactions on Electron Devices</u> , Vol. 45, No. 7, pp. 1438-1443, July 1998					
Examiner <i>miller D. C.</i>				Date Considered <i>12/10/02</i>			
Examiner: Initial if citation considered, whether or not citation is in conference with MPEP 609; Draw line through citation if not conformance and not considered. Include a copy of this form with the next communication to applicant.							

